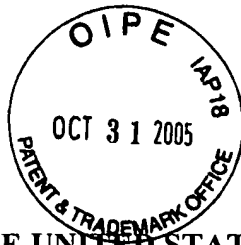


S/N 09/483,881



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Kie Y. Ahn et al.	Examiner:	Ha T. Nguyen
Serial No.:	09/483,881	Group Art Unit:	2812
Filed:	January 18, 2000	Docket:	303.672US1
Title:	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION		

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants have included the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p). Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

11/01/2005 JBALINAN 00000002 09483881

01 FC:1806

180.00 OP

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.


Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 349-9587

Date October 27, 2005 By 
Suneel Arora
Reg. No. 42,267

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 27 day of October, 2005.

Name KATE GANNON

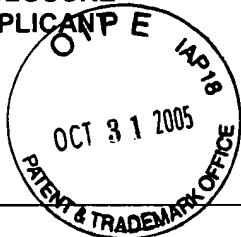
Signature 

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO

INFORMATION DISCLOSURE**STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

Application Number	09/483,881
Filing Date	January 18, 2000
First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha

Sheet 1 of 1

Attorney Docket No: 303.672US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
	US-2003/0034560A1	02/20/2003	Matsuse, K., et al.	05/05/2000
	US-4,824,544	04/25/1989	Mikalesen, D. J., et al.	10/29/1987
	US-4,933,743	06/12/1990	Thomas, M. E., et al.	08/14/1989
	US-5,071,518	12/10/1991	Pan, J. T.	10/24/1989
	US-5,374,849	12/20/1994	Tada, K.	03/01/1993
	US-5,401,680	03/28/1995	Abt, N. E., et al.	02/18/1992
	US-5,693,563	12/02/1997	Teong, S.	07/15/1996
	US-5,789,264	08/04/1998	Chung, J.	09/26/1996
	US-5,840,625	11/24/1998	Feldner, K.	10/04/1996
	US-5,899,740	05/04/1999	Kwon, C.	09/04/1997
	US-5,968,327	10/19/1999	Kobayashi, M., et al.	02/12/1998
	US-6,028,362	02/22/2000	Omura, M.	05/11/1998
	US-6,143,671	11/07/2000	Sugai, K.	11/19/1998
	US-6,150,214	11/21/2000	Kaeriyama, T.	11/20/1998
	US-6,169,024	01/02/2001	Hussein, M. A.	09/30/1998
	US-6,174,804	01/16/2001	Hsu, C.	09/24/1998
	US-6,215,186	04/10/2001	Konecni, A. J., et al.	01/05/1999
	US-6,258,707	07/10/2001	Uzoh, C. E.	01/07/1999
	US-6,288,447	09/11/2001	Amishiro, H., et al.	07/15/1999
	US-6,417,094	07/09/2002	Zhao, B., et al.	12/31/1998
	US-6,589,863	07/08/2003	Usami, T.	12/23/1999

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T ²
--------------------	---------------------	------------------	---	----------------

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		BHANSALI, S., et al., "Selective seeding of copper films on polyimide-patterned silicon substrate, using ion implantation", <u>Sensors and Actuators A: Physical</u> , 52(1), (March 1996), 126-131	

EXAMINER**DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached